

**IN THE CLAIMS**

**CLAIM 1 (Previously Presented)** A structure comprising:

a substrate having a surface;

a plurality of compliant elongated electrical conductors extending away from said surface;

each of said elongated electrical conductors having a first end affixed to said surface and a second end projecting away from said surface;

there being a plurality of said second ends; and

a means for positioning and maintaining said plurality of said second ends in substantially fixed positions.

**CLAIM 2 (Original)** A structure according to claim 1 wherein said first end is affixed to said surface at an electrical contact location.

**CLAIM 3 (Currently Amended)** A structure according to claim 1 wherein said means for positioning and maintaining is a plurality of sheets of material each having a plurality of ~~opening~~ openings therein through which said second ends project.

**CLAIM 4 (Original)** A structure according to claim 1 wherein at said second end there is disposed a structure selected from the group consisting of a protuberance and a sharp spike.

CLAIM 5 (Original) A structure according to claim 3 wherein said plurality of sheets are formed from a material selected from the group consisting of a rigid material and a compliant material.

CLAIM 6 (Original) A structure according to claim 3 wherein each of said sheets comprise a plurality of openings, said elongated electrical conductors are disposed against the sides or said openings of at least two of said sheets.

CLAIM 7 (Original) A structure according to claim 3 wherein said sheet is spaced apart from said surface by a flexible support.

CLAIM 8 (Original) A structure according to claim 7 wherein said flexible support is selected from the group consisting of a spring and an elastomeric material.

CLAIM 9 (Original) A structure according to claim 1 wherein said elongated electrical conductors have a shape selected from the group consisting of linear, piece wise linear, curved and combinations thereof.

CLAIM 10 (Original) A structure according to claim 7 wherein said sheet and said flexible support forms a space containing said plurality of elongated electrical conductors.

CLAIM 11 (Original) A structure according to claim 10 wherein said space is filled with a flexible material.

CLAIM 12 (Original) A structure according to claim 11 wherein said flexible material is an elastomeric material.

CLAIM 13 (Original) A structure according to claim 3 wherein at least one of said sheets is a sheet of electrically conductive material which has a top surface and

a bottom surface and said openings have a sidewall, a dielectric material coats said top surface and said bottom surface and said sidewall.

CLAIM 14 (Original) A structure according to claim 1 wherein said plurality of elongated electrical conductors are distributed into a plurality of groups.

CLAIM 15 (Previously Presented) A structure according to claim 14 wherein said plurality of groups are arranged in an array.

CLAIM 16 (Original) A structure according to claim 1 wherein said structure is a probe for an electronic device.

CLAIM 17 (Original) A structure according to claim 16 wherein said electronic device is selected from the group consisting of an integrated circuit chip and a packaging substrate.

CLAIM 18 (Original) A structure according to claim 15 wherein each of said groups corresponds to an integrated circuit chip on a substrate containing a plurality of said integrated circuit chips.

CLAIM 19 (Original) A structure according to claim 18 wherein said substrate containing said plurality of integrated circuit chips is a wafer of said integrated circuit chips.

CLAIM 20 (Original) An apparatus for using said structure of claim 1 to test an electronic device comprising: means for holding said structure of claim 1, means for retractably moving said structure of claim 1 towards and away from said electronic device so that said second ends contact electrical contact locations on said electronic device, and means for applying electrical signals to said elongated electrical conductors.

CLAIM 21 (Previously Presented) A structure according to claim 4 wherein said protuberance is sphere like.

CLAIM 22 (Currently Amended) A structure according to 3 wherein said structure is for electrical connection to device and wherein said means for ~~maintaining and positioning~~ and maintaining comprises a first sheet of material having a temperature coefficient of expansion substantially matched to said electronic device, said first sheet has a first side and a second side, a first sheet of dielectric material disposed on said first side and a second sheet of dielectric material disposed on said second side, ~~[[d]]~~ an electrically conductive material having a plurality of first through holes therein, and a sheet of a dielectric material having a plurality of second through holes therein, said first through holes are aligned with said second through holes, said first through holes have a smaller diameter than said second through holes to provide a means for preventing said elongated electrical conductors from electrically contacting said sheet of electrically conductive material.

CLAIM 23 (Original) A structure according to claim 22 wherein sheet or electrically conductive material has a first side and a second side, said sheet of dielectric material is disposed on either of said first side and said second side of said sheet of electrically conductive material.

CLAIM 24 (Original) A structure according to claim 23, where there is disposed on said first side and said second side of said sheet of electrically conductive material a layer of said dielectric material.

CLAIM 25 (Original) A structure according to claim 3 wherein said sheet comprises a sheet of rigid material having a plurality of through holes therein, said sheet contains a dielectric material to provide a means for preventing said elongated electrical conductors from electrically contacting said sheet of electrically conductive material.

**CLAIM 26 (Original)** A structure according to claim 3 wherein said sheet comprises a sheet of dielectric material having a plurality of through holes therein, said sheet contains a sheet of a rigid material disposed in contact with said sheet of dielectric material, said sheet of rigid material has an opening therein exposing a plurality of said through holes to provide a means for support of said dielectric material.

**CLAIM 27 (Original)** A structure according to claim 26 wherein said sheet is spaced apart from said surface by a flexible support, said sheet of rigid material is disposed on said flexible support.

**CLAIM 28 (Withdrawn)** An apparatus for making electrical contact with a plurality of bond pads on an integrated circuit device comprising: a first fan out substrate having a first surface; said first surface having a plurality of contact locations; a plurality of ball bonds attached to said plurality of contact locations; a plurality of wires extending outward from said ball bonds, away from said first surface on fan out substrate; a plurality of ball shaped contacts on the ends of said plurality of wires; and a means for maintaining said plurality of balls in substantially fixed positions.

**CLAIM 29 (Withdrawn)** A high density probe according to claim 28, wherein said fan out substrate is selected from the group consisting of: multilayer ceramic substrates with thick film wiring; multilayer ceramic substrates with thin film wiring; metallized ceramic substrates with thin film wiring; epoxy glass laminate substrates with copper wiring; and silicon substrates with thin film wiring.

**CLAIM 30 (Withdrawn)** A high density probe according to claim 28, further including a preformed frame of foamed elastomer material surrounding clusters, groupings, or arrays of said probes.

CLAIM 31 (Withdrawn) A high density probe according to claim 30, further including a layer of elastomer material surrounding said probes in said cluster.

CLAIM 32 (Withdrawn) A high density probe according to claim 31, wherein said means for maintaining is a sheet of Invar material that has a thin coating of a polymer material and a plurality of openings corresponding to said plurality of ball shaped contacts.

CLAIM 33 (Withdrawn) A high density probe according to claim 31, further including a sheet of rigid material with a plurality of large diameter openings corresponding to said plurality of ball shaped contacts.

CLAIM 34 (Withdrawn) A high density probe according to claim 33, further including a sheet of polymer material with a plurality of small diameter openings corresponding to said plurality of ball shaped contacts place on top of said sheet of Invar material.

CLAIM 35 (Withdrawn) A high density probe according to claim 37, further including a sheet of polymer material with a plurality of openings corresponding to said plurality of ball shaped contacts.

CLAIM 36 (Withdrawn) A high density probe according to claim 35, further including a frame of rigid material attached to said sheet of polymer material with said plurality of openings corresponding to said plurality of ball shaped contacts.

CLAIM 37 (Withdrawn) A high density probe according to claim 32, further including a thick frame of rigid material attached to said sheet of Invar material with said thin coating of a polymer material and said plurality of openings corresponding to said plurality of ball shaped contacts.

CLAIM 38 (Withdrawn) A high density probe according to claim 33, further including a plurality of probes arrays corresponding to the location of a plurality of IC devices on a wafer.

CLAIM 39 (Withdrawn) A high density probe according to claim 30, further including a sheet of rigid material that has a thin coating of a polymer material and a plurality of openings corresponding to said plurality of ball shaped contacts.

CLAIM 40 (Withdrawn) A structure according to claim 1 wherein said substantially fixed positions substantially correspond to electrical contact locations on a device to be tested by said probe.

CLAIM 41 (Original) A method comprising:

providing a substrate having a surface;

forming a plurality of elongated electrical conductors extending away from said surface;

each of said elongated electrical conductors having a first end affixed to said surface and a second end projecting away from said surface;

there being a plurality of said second ends;

providing a means for maintaining said plurality of said second ends in substantially fixed positions with respect to each other.

CLAIM 42 (Currently Amended) A structure according to claim [[3]] 1 wherein said means for positioning and maintaining is a sheet [[is]] formed and from a

material selected from the group consisting of Invar, Cu/Invar/Cu, molybdenum[~~(,)~~] and polyimides.

CLAIM 43 (Currently Amended) A structure according to claim ~~[[3]]~~ 1 wherein said means for positioning and maintaining a sheet ~~[[is]]~~ formed from a material selected from the group consisting of a metal, a polymer, a semiconductor and dielectric.

CLAIM 44 (Original) A structure according to claim 43 wherein said dielectric is selected from the group consisting of a ceramic and a glass.

CLAIM 45 (Original) A structure according to claim 1 where at least a part of said elongated conductor is coated with a hard coat.

CLAIM 46 (Original) A structure according to claim 45 wherein said hard coat is selected from the group consisting of Pd, Pt, Ni, Au, Rh, Ru, Re, Cu, Co alloys thereof and combinations thereof.

CLAIM 47 (Original) A structure according to claim 3 wherein at least one of said sheets is a sheet of electrically conductive material having a plurality of through holes therein, said sheet of electrically conductive material material contains a dielectric material to provide a means for preventing said elongated electrical conductors from electrically contacting said sheet of electrically conductive material.

CLAIM 48 (Previously Presented) A structure according to claim 1 wherein said compliant elongated electrical conductor is shaped to compliantly respond when the said compliant elongated electrical conductors are pressed against and withdraw from a surface against which said second ends are pressed.



**CLAIM 49 (Previously Presented)** A structure according to claim 1 wherein said means for maintaining comprises a sheet of material comprising openings comprising a large region and a small region.

**CLAIM 50 (Currently Amended)** A method according to claim 28, wherein said compliant wire elongated electrical conductor is shaped to compliantly respond when the said compliant elongated electrical conductors are pressed against and withdraw from a surface against which said second ends are pressed.

**CLAIM 51 (Previously Presented)** A method according to claim 41 wherein said means for maintaining comprises openings comprising a large region and a small region, said compliant elongated electrical conductors are first inserted through said large region and then moved to said small region.

**CLAIM 52 (Previously Presented)** A structure comprising:

a substrate having a surface;

a plurality of elongated electrical conductors extending away from said surface;

each of said elongated electrical conductors having a first end affixed to said surface and a second end projecting away from said surface;

said second end is at a non-orthogonal angle with respect to said surface;

there being a plurality of said second ends; and

a means for positioning and maintaining said plurality of said second ends in substantially fixed positions.

CLAIM 53 (Previously Presented) A structure according to claim 52 wherein said non-orthogonal angle is from between 5 degrees and 60 degrees.

CLAIM 54 (Previously Presented) A structure according to claim 52 wherein said elongated electrical conductor comprises a bend.

CLAIM 55 (Previously Presented) An apparatus for making electrical contact with a plurality of bond pads on an integrated circuit device comprising: a first fan out substrate having a first surface; said first surface having a plurality of contact locations; a plurality of ball bonds attached to said plurality of contact locations; a plurality of wires extending outward from said ball bonds, away from said first surface fan out substrate; a plurality of ball shaped contacts on the ends of said plurality of wires; and a means for maintaining said plurality of balls in substantially fixed positions; said wire has a first end and electrically connected to a corresponding contact location and a second end extending outwardly from said surface at a non-orthogonal angle to said surface.

CLAIM 56 (Previously Presented) A structure according to claim 55 wherein said non-orthogonal angle is from between 5 degrees and 60 degrees.

CLAIM 57 (Previously Presented) A structure according to claim 55 wherein said elongated electrical conductor comprises a bend.

CLAIM 58 (Added) A structure according to claim 52 wherein said means is a sheet of material comprising a plurality of openings through which said second ends project.

CLAIM 59 (Added) A structure according to claim 1 wherein said means for positioning and maintaining comprises at least one sheet of material comprising a plurality of openings through which said second ends project.

CLAIM 60 (Added) A structure according to claim 58 wherein of said at least one sheet is a sheet of electrically conductive material which has a top surface and a bottom surface and said openings have a sidewall, a dielectric material coats said top surface and said bottom surface and said sidewall.

CLAIM 61 (Added) A structure according to claim 1 wherein said structure is an electronic packaging structure.

CLAIM 62 (Added) A structure according to claim 3 wherein said at least one of sheet is formed from a material selected from the group consisting of a metal, a polymer, a semiconductor and dielectric.

CLAIM 63 (Added) A structure according to claim 3 wherein at least one of said plurality of sheets is formed from a material selected from the group consisting of Invar, Cu/Invar/Cu, molybdenum and polyimides.